

74F573 Octal D-Type Latch with 3-STATE Outputs

General Description

The 74F573 is a high speed octal latch with buffered common Latch Enable (LE) and buffered common Output Enable (\overline{OE}) inputs.

This device is functionally identical to the 74F373 but has different pinouts.

Features

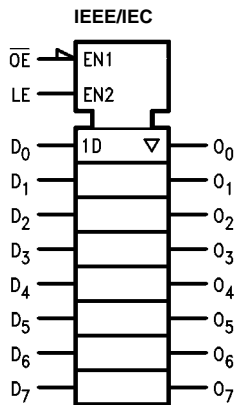
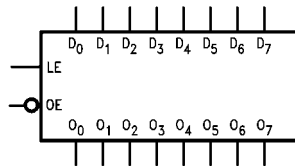
- Inputs and outputs on opposite sides of package allowing easy interface with microprocessors
- Useful as input or output port for microprocessors
- Functionally identical to 74F373
- 3-STATE outputs for bus interfacing
- Guaranteed 4000V minimum ESD protection

Ordering Code:

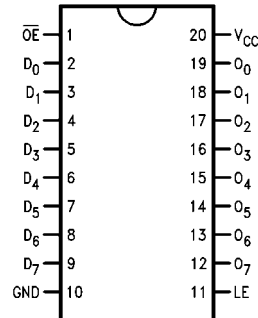
Order Number	Package Number	Package Description
74F573SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74F573SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F573PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbols



Connection Diagram



Unit Loading/Fan Out

Pin Names	Description	U.L. HIGH/LOW	Input I_{IH}/I_{IL} Output I_{OH}/I_{OL}
D ₀ -D ₇	Data Inputs	1.0/1.0	20 μ A/-0.6 mA
LE	Latch Enable Input (Active HIGH)	1.0/1.0	20 μ A/-0.6 mA
\overline{OE}	3-STATE Output Enable Input (Active LOW)	1.0/1.0	20 μ A/-0.6 mA
O ₀ -O ₇	3-STATE Latch Outputs	150/40(33.3)	-3 mA/24 mA (20 mA)

Functional Description

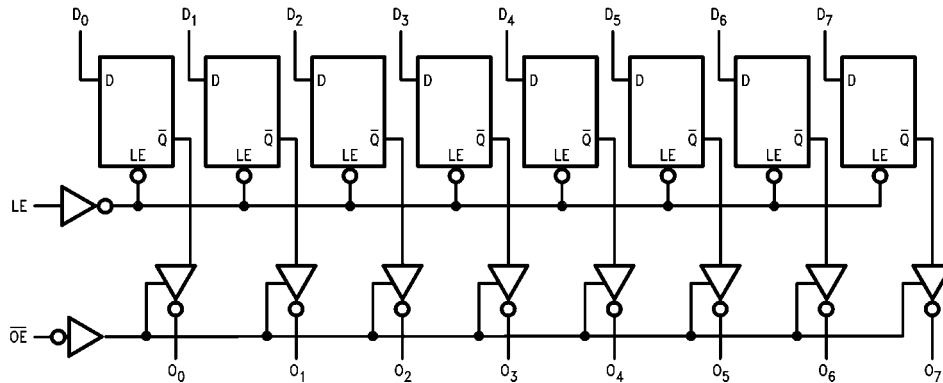
The 74F573 contains eight D-type latches with 3-state output buffers. When the Latch Enable (LE) input is HIGH, data on the D_n inputs enters the latches. In this condition the latches are transparent, i.e., a latch output will change state each time its D input changes. When LE is LOW the latches store the information that was present on the D inputs a setup time preceding the HIGH-to-LOW transition of LE. The 3-state buffers are controlled by the Output Enable (\overline{OE}) input. When \overline{OE} is LOW, the buffers are in the bi-state mode. When \overline{OE} is HIGH the buffers are in the high impedance mode but this does not interfere with entering new data into the latches.

Function Table

Inputs			Outputs
\overline{OE}	LE	D	O
L	H	H	H
L	H	L	L
L	L	X	O ₀
H	X	X	Z

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
O₀ = Value stored from previous clock cycle

Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings(Note 1)

Storage Temperature	-65°C to +150°C
Ambient Temperature under Bias	-55°C to +125°C
Junction Temperature under Bias	-55°C to +150°C
V _{CC} Pin Potential to Ground Pin	-0.5V to +7.0V
Input Voltage (Note 2)	-0.5V to +7.0V
Input Current (Note 2)	-30 mA to +5.0 mA
Voltage Applied to Output in HIGH State (with V _{CC} = 0V)	
Standard Output	-0.5V to V _{CC}
3-STATE Output	-0.5V to +5.5V
Current Applied to Output in LOW State (Max)	twice the rated I _{OL} (mA)
ESD Last Passing Voltage (Min)	4000V

Recommended Operating Conditions

Free Air Ambient Temperature	0°C to +70°C
Supply Voltage	+4.5V to +5.5V

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

DC Electrical Characteristics

Symbol	Parameter	Min	Typ	Max	Units	V _{CC}	Conditions
V _{IH}	Input HIGH Voltage	2.0			V		Recognized as a HIGH Signal
V _{IL}	Input LOW Voltage			0.8	V		Recognized as a LOW Signal
V _{CD}	Input Clamp Diode Voltage			-1.2	V	Min	I _{IN} = -18 mA
V _{OH}	Output HIGH Voltage	10% V _{CC} 10% V _{CC} 5% V _{CC} 5% V _{CC}	2.5 2.4 2.7 2.7		V	Min	I _{OH} = -1 mA I _{OH} = -3 mA I _{OH} = -1 mA I _{OH} = -3 mA
V _{OL}	Output LOW Voltage	10% V _{CC}		0.5	V	Min	I _{OL} = 24 mA
I _{IH}	Input HIGH Current			20.0 5.0	μA	Max	V _{IN} = 2.7V
I _{BVI}	Input HIGH Current Breakdown Test			7.0	μA	Max	V _{IN} = 7.0V
I _{CEX}	Output HIGH Leakage Current			50	μA	Max	V _{OUT} = V _{CC}
V _{ID}	Input Leakage Test	4.75			V	0.0	I _{ID} = 1.9 μA All Other Pins Grounded
I _{OD}	Output Leakage Circuit Current			3.75	μA	0.0	V _{ID} = 150 mV All Other Pins Grounded
I _{IL}	Input LOW Current			-0.6	mA	Max	V _{IN} = 0.5V
I _{OZH}	Output Leakage Current			50	μA	Max	V _{OUT} = 2.7V
I _{OZL}	Output Leakage Current			-50	μA	Max	V _{OUT} = 0.5V
I _{OS}	Output Short-Circuit Current	-60		-150	mA	Max	V _{OUT} = 0V
I _{ZZ}	Bus Drainage Test			500	μA	0.0V	V _{OUT} = 5.25V
I _{CCL}	Power Supply Current		35	55	mA	Max	V _O = LOW
I _{CCZ}	Power Supply Current		35	55	mA	Max	V _O = HIGH Z

AC Electrical Characteristics

Symbol	Parameter	T _A = +25°C V _{CC} = +5.0V C _L = 50 pF			T _A = -55°C to +125°C V _{CC} = +5.0V C _L = 50 pF		T _A = 0°C to +70°C V _{CC} = +5.0V C _L = 50 pF		Units
		Min	Typ	Max	Min	Max	Min	Max	
t _{PLH}	Propagation Delay	3.0	5.3	7.0	3.0	9.0	3.0	8.0	ns
t _{PHL}	D _n to O _n	2.0	3.7	6.0	2.0	7.0	2.0	6.5	
t _{PLH}	Propagation Delay	5.0	9.0	11.0	5.0	13.5	5.0	12.0	ns
t _{PHL}	LE to O _n	3.0	5.2	7.0	3.0	7.5	3.0	7.0	
t _{PZH}	Output Enable Time	2.0	5.0	8.0	2.0	10.0	2.0	9.0	ns
t _{PZL}		2.0	5.6	8.5	2.0	10.0	2.0	9.5	
t _{PHZ}	Output Disable Time	1.5	4.5	5.5	1.5	7.0	1.5	6.5	ns
t _{PLZ}		1.5	3.8	5.5	1.5	5.5	1.5	5.5	

AC Operating Requirements

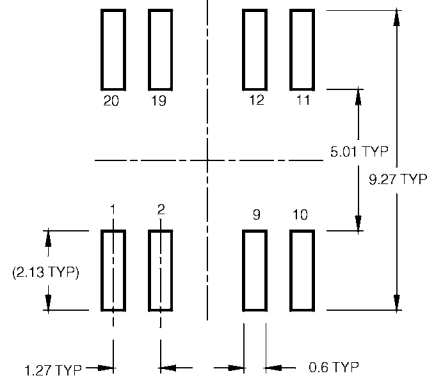
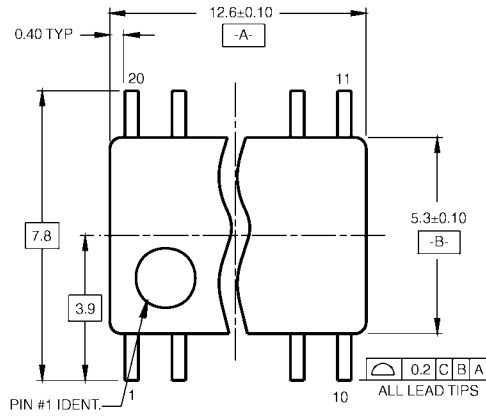
Symbol	Parameter	T _A = +25°C V _{CC} = +5.0V		T _A = -55°C to +125°C V _{CC} = +5.0V		T _A = 0°C to +70°C V _{CC} = +5.0V		Units
		Min	Max	Min	Max	Min	Max	
t _S (H)	Setup Time, HIGH or LOW	2.0		2.0		2.0		ns
t _S (L)	D _n to LE	2.0		2.0		2.0		
t _H (H)	Hold Time, HIGH or LOW	3.0		3.0		3.0		ns
t _H (L)	D _n to LE	3.5		4.0		3.5		
t _W (H)	LE Pulse Width, HIGH	4.0		4.0		4.0		ns

Physical Dimensions inches (millimeters) unless otherwise noted

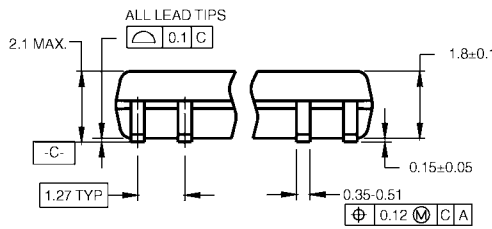


**20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
Package Number M20B**

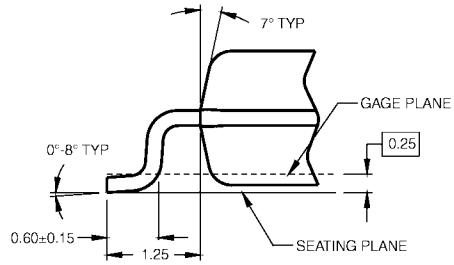
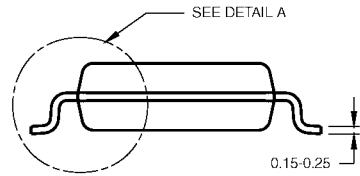
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS



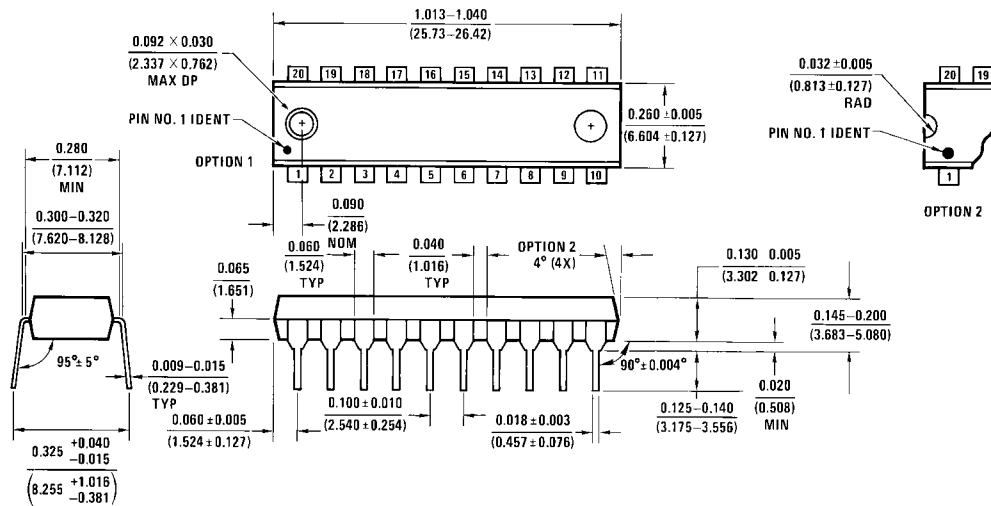
DETAIL A

- NOTES:
- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
 - B. DIMENSIONS ARE IN MILLIMETERS.
 - C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M20DRevB1

**20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M20D**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



N20A (REV G)

**20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide
Package Number N20A**

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